



Title		
<b>Hardware Pace Detect Circuit</b>		
Size	Number	Revision
A		<b>A</b>
Date:	5/30/2013	Sheet 1 of 1
File:	C:\Userdata\...\ECG Pace Board.Sch	Drawn By: <b>Tony Calabria</b>

Comment	Description	Designator	Footprint	LibRef	Quantity
1uF	Capacitor, [NoValue]	C1, C7	0603	CAP, CAP_603	2
10nF	Capacitor	C2	0603	CAP	1
0.1uF		C3, C4, C5, C6	0603	CAP_603	4
EXT_GND		J1	1PIN	1PIN	1
VCC		J2	1PIN	1PIN	1
HEADER 5X2		J3	CONN5X2	HEADER 5X2	1
GND JMP	3 Position Jumper _ .1" spacing	JP1	3pos_jump	3POS_JUMPER	1
392k		R1	0603	RES1	1
0		R2	0603	RES1	1
10.2k		R3	0603	RES1	1
10k		R4, R6, R7, R8	0603	RES1	4
8.06k		R5	0603	RES1	1
2M		R9, R10	0603	RES1	2
1M		R11	0603	RES1	1
PACE RESET	Panasonic EVQ-PH SMT tact switch	S1	PAN_EVQP2	PAN_EVQPH	1
VPACE2	Test Point - Single .025" Pin	TP1	test_point2	TP_.025	1
TP_.025	Test Point - Single .025" Pin	TP2, TP3, TP4	test_point2	TP_.025	3
GND1	Test Point - Single .025" Pin	TP5	test_point2	TP_.025	1
GND2	Test Point - Single .025" Pin	TP6	test_point2	TP_.025	1
OPA348AIDCKR		U1	5-SOT(DCK)	OPA348DCK	1
TLV3401CDBVT		U2, U3	5-SOT(DBV)	TLV370X	2
SN74LVC2G00DCTR		U4	8-TSSOP(DCT)	SN74LVC2G08	1

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